

Title (en)

Copper alloy having excellent hot rollability and excellent adhesion strength of plated surface thereof when heated.

Title (de)

Kupferlegierung mit hervorragender Warmwälzbarkeit und sehr guter Beständigkeit gegen Abblättern einer plattierten Oberfläche während der Heizung derselben.

Title (fr)

Alliage de cuivre présentant une excellente aptitude au laminage à chaud et une très bonne résistance à l'écaillage d'une surface plaquée et chauffée.

Publication

**EP 0384260 A1 19900829 (EN)**

Application

**EP 90102686 A 19900212**

Priority

JP 4090889 A 19890221

Abstract (en)

A copper alloy consists essentially by weight percent of 0.5 to 3% Ni, 0.5 to 2.5% Sn, 0.05 to 0.9% Si, 0.1 to 2% Zn, 0.025 to 0.25% Fe, and the balance of Cu and inevitable impurities. The inevitable impurities include C in an amount of not more than 10 ppm. The obtained copper alloy possesses improved hot rollability and exhibits excellent adhesion strength of a plated surface thereof when heated, while having satisfactory strength and platability.

IPC 1-7

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IPC 8 full level

**C22C 9/02** (2006.01); **C22C 9/04** (2006.01); **C22C 9/06** (2006.01)

CPC (source: EP KR US)

**C22C 9/02** (2013.01 - EP US); **C22C 9/04** (2013.01 - EP US); **C22C 9/06** (2013.01 - EP KR US)

Citation (search report)

- [A] EP 0189637 A1 19860806 - KOBE STEEL LTD [JP]
- [A] FR 2338585 A2 19770812 - OLIN CORP [US]
- [A] DE 756035 C 19520417 - VER DEUTSCHE METALLWERKE AG
- [A] DE 1558474 A1 19700319 - DIES DR ING KURT
- [Y] FR 2501556 A1 19820917 - KABEL METALLWERKE GHH [DE]
- [Y] E. HERRMANN et al.: "Handbook on continuous casting", 1988, Aluminium-Verlag, Düsseldorf, DE

Cited by

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DOCDB simple family (publication)

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